RENESAS

HZM6.8Z4MWA

Silicon Planar Zener Diode for Surge Absorb

REJ03G0369-0100 Rev.1.00 Oct 01, 2004

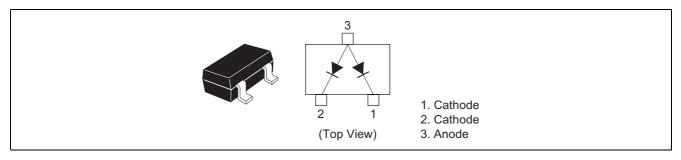
Features

- HZM6.8Z4MWA has two devices in a monolithic, and can absorb surge.
- Low capacitance (C = 4.0 pF Typ / 4.5 pF max) and can protect ESD of signal line.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

| Type No. | Laser Mark | Package Code |
|-------------|------------|--------------|
| HZM6.8Z4MWA | N2 | MPAK |

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Symbol | Value | Unit |
|--------|-------------|---|
| Pd * | 200 | mW |
| Тј | 150 | °C |
| Tstg | –55 to +150 | °C |
| | Pd * Tj | Pd * 200 Tj 150 |

Note: two device total, See Fig.2.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

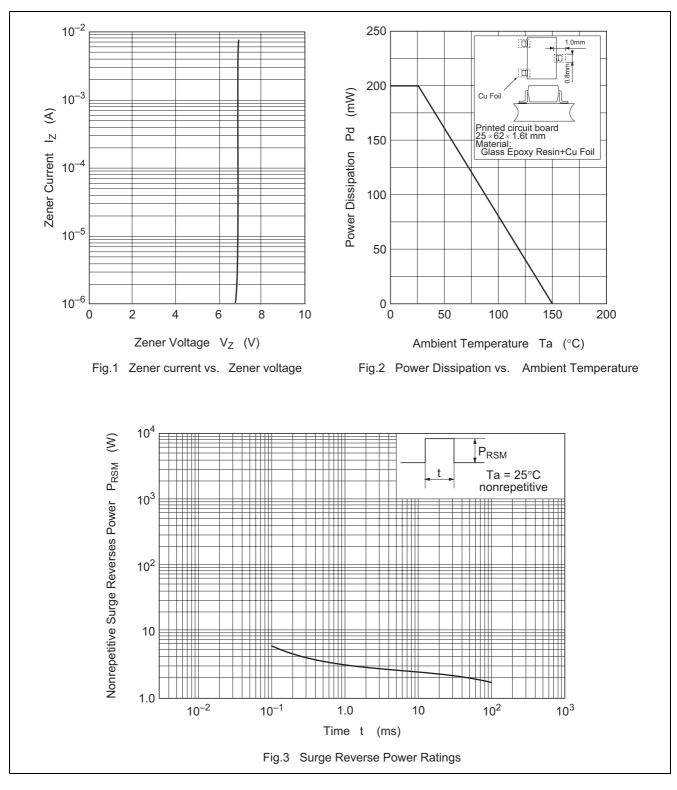
| ltem | Symbol | Min | Тур | Max | Unit | Test Condition |
|-------------------------------|----------------|------|-----|------|------|---|
| Zener voltage | Vz | 6.47 | — | 7.00 | V | I _Z = 5 mA, 40 ms pulse |
| Reverse current | I _R | | — | 2 | μA | $V_R = 3.5 V$ |
| Capacitance | С | | 4.0 | 4.5 | pF | $V_R = 0 V$, f = 1 MHz |
| Dynamic resistance | r _d | | — | 30 | Ω | $I_Z = 5 \text{ mA}$ |
| ESD-Capability * ² | — | 8 | — | | kV | C = 150 pF, R = 330 Ω , Both forward and |
| | | | | | | reverse direction 10 pulse |

Notes: 1. Per one device.

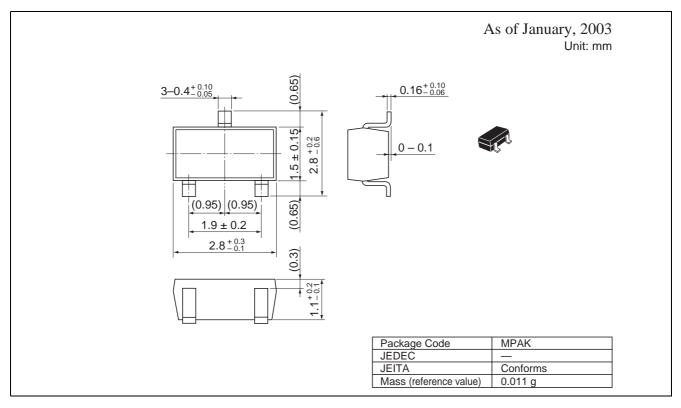
2. Failure criterion ; $I_R>2~\mu A$ at V_R = 3.5 V.



Main Characteristic



Package Dimensions





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